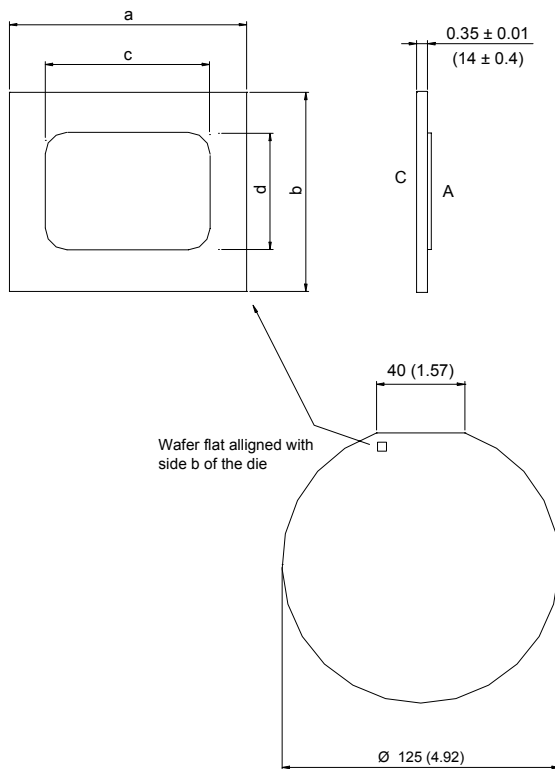


Fred Die in Wafer Form



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).

2. CONTROLLING DIMENSION (MILS):

3. DIMENSIONS AND TOLERANCES:

- a = 1.524 + 0, -0.01  
(60 + 0, -0.4)
- b = 1.168 + 0, -0.01  
(45.98 + 0, -0.4)
- c = 1.310 + 0, -0.01  
(51.57 + 0, -0.4)
- d = 0.954 + 0, -0.01  
(37.56 + 0, -0.4)

4. LETTER DESIGNATION:

- A = Anode (Top Metal)
- C = Cathode (Back Metal)

5. SAWING:

- Recommended Blade
- SEMITEC S1025 QS00 Blade
- Sawing Street
- 0.05 + 0, -0.005
- (2 + 0, -0.2)

NOT TO SCALE

Reference IR Packaged Part: MURD620CT Series

**Electrical Characteristics (Wafer Form)**

Parameters	Units	Test Conditions
$V_{FM}$ Maximum Forward Voltage	1.0 V	$T_J = 25^\circ\text{C}$ , $I_F = 3\text{ A}$
$V_{RRM}$ Minimum Reverse Breakdown Voltage	200 V	$T_J = 25^\circ\text{C}$ , $I_{RRM} = 100\ \mu\text{A}$
$I_{RM}$ Max. Reverse Leakage Current	5 $\mu\text{A}$	$T_J = 25^\circ\text{C}$ , $V_{RRM} = 200\text{ V}$
$t_{rr}$ Typ. Reverse Recovery Time	25 ns	$I_F = 1\text{ A}$ , $di_F/dt = 50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$

**Mechanical Data**

Nominal Back Metal Composition, Thickness	Cr - Ni - Ag (1 KA - 2 KA - 3 KA)
Nominal Front Metal Composition, Thickness	99% Al, 1% Si (3 microns)
Chip Dimensions	0.060" x 0.046" (see drawing)
Reject Ink Dot Size	0.25 mm diameter minimum
Recommended Storage Environment	Storage in original container, in dessicated nitrogen, with no contamination

**Packaging**

Device #	Description	Minimum Order Quantity Die in Sale Package
FD060xxx5 <b>B</b>	Inked Probed Unsawn Wafer (Wafer in Box)	4800
FD060xxx5 <b>R</b>	Probed Die in Tape & Reel	6000
FD060xxx5 <b>P</b>	Probed Die in Waffle Pack	4800
FD060xxx5 <b>F</b>	Inked Probed Sawn Wafer on Film	4800

### Ordering Information Table

Device Code															
	<table border="1" style="margin: auto;"> <tr> <td style="padding: 5px;">FD</td> <td style="padding: 5px;">060</td> <td style="padding: 5px;">U</td> <td style="padding: 5px;">02</td> <td style="padding: 5px;">A</td> <td style="padding: 5px;">5</td> <td style="padding: 5px;">B</td> </tr> <tr> <td style="text-align: center;">①</td> <td style="text-align: center;">②</td> <td style="text-align: center;">③</td> <td style="text-align: center;">④</td> <td style="text-align: center;">⑤</td> <td style="text-align: center;">⑥</td> <td style="text-align: center;">⑦</td> </tr> </table>	FD	060	U	02	A	5	B	①	②	③	④	⑤	⑥	⑦
FD	060	U	02	A	5	B									
①	②	③	④	⑤	⑥	⑦									
<p><b>1</b> - Fred Die</p> <p><b>2</b> - Chip Dimension in Mils:      060 = 060x046 square</p> <p><b>3</b> - Process                              U = UltraFast</p> <p><b>4</b> - Voltage code Vrrm (*100) eg: 02 = 200V</p> <p><b>5</b> - Chip surface metallization:    A = Aluminium (anode), Silver (cathode)</p> <p><b>6</b> - Wafer diameter in inches</p> <p><b>7</b> - Packaging:                            B = Inked Probed Unsawn Wafer (Wafer in box)</p>															

Data and specifications subject to change without notice.  
 This product has been designed and qualified for Industrial Level.  
 Qualification Standards can be found on IR's Web site.